

REMOVAL METHOD OF CARRIER PLATE

ABSTRACT OF THE DISCLOSURE

There is provided a removal method of a carrier plate used when the carrier plate is removed from a workpiece bonded to a region excluding an outer rim part in a front surface of the carrier plate by a temporary bonding layer. This removal method of a carrier plate includes a temporary bonding layer removal step of removing part or all of an outer rim part of the temporary bonding layer, a holding step of holding the workpiece from the upper side by a holding unit after removing part or all of the outer rim part of the temporary bonding layer, and a carrier plate removal step of removing the carrier plate from the workpiece by applying a downward force to the outer rim part of the carrier plate from the side of the front surface.

[Fig. 2A]